



## 30V Complementary Enhancement-Mode MOSFET

### General Description

- Low gate charge.
- Use as a load switch.
- Use in PWM applications

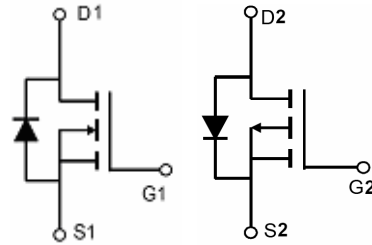
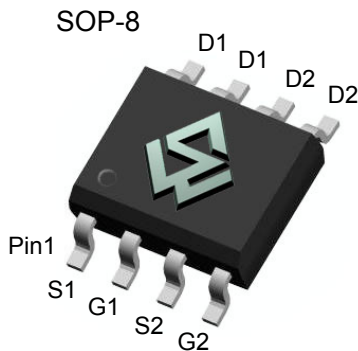
### Product Summary

N-Channel

- $BV_{DSS} = 30V$
- $R_{DS(on)} (@VGS = 10V) < 30m\Omega$
- $R_{DS(on)} (@VGS = 4.5V) < 42m\Omega$

P-Channel

- $BV_{DSS} = -30V$
- $R_{DS(on)} (@VGS = -10V) < 28m\Omega$
- $R_{DS(on)} (@VGS = -4.5V) < 44m\Omega$



### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum		Units
		N-Channel	P-Channel	
Drain-Source Voltage	$V_{DS}$	30	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Drain Current ( $T_A=25^\circ C$ )	$I_D$	6	-6.5	A
Drain Current ( $T_A=75^\circ C$ )		4	-4.5	A
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	24	-28	A
Power Dissipation <sup>b</sup> ( $T_A=25^\circ C$ )	$P_D$	2.5	2.5	W
Power Dissipation <sup>b</sup> ( $T_A=75^\circ C$ )		1.0	1.0	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ +150	-55 ~ +150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Maximum		Units
		N-Channel	P-Channel	
Junction-to-Ambient <sup>a</sup> ( $t \leq 10s$ )	$R_{\theta JA}$	50	60	$^\circ C/W$
Junction-to-Ambient <sup>a,d</sup> (Steady-State)		80	90	$^\circ C/W$
Junction-to-Lead (Steady-State)	$R_{\theta JL}$	25	35	$^\circ C/W$



N-Channel Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu\text{A}$	30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V$			1	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1		2.5	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 6A$			30	$\text{m}\Omega$
		$V_{GS} = 4.5V, I_D = 5A$			42	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 10V, I_D = 6A$		30		S
<b>Drain-Source Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0V, I_S = 1.0A$			1.2	V
$I_S$	Maximum Body-Diode Continuous Current				2.5	A
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 15V, V_{GS} = 0V$ $f = 1.0\text{MHz}$		740		$\text{pF}$
$C_{oss}$	Output Capacitance			186		$\text{pF}$
$C_{rss}$	Reverse Transfer Capacitance			82		$\text{pF}$
<b>Switching Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{DS} = 15V, I_D = 6A$ $V_{GS} = 10V$		15		nC
$Q_{gs}$	Gate-Source Charge			2.5		nC
$Q_{gd}$	Gate-Drain Charge			3.3		nC
$t_{D(ON)}$	Turn-On Delay Time	$V_{DD} = 15V, I_D = 1A$ $V_{GS} = 10V$ $R_{GEN} = 3\text{ohm}$		11		ns
$t_r$	Turn-On Rise Time			6		ns
$t_{D(OFF)}$	Turn-Off Delay Time			27		ns
$t_f$	Turn-Off Fall Time			12		ns

- Repetitive rating, Pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ\text{C}$
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using  $\leq 10\text{s}$  junction-to-ambient thermal resistance.
- The value of  $R_{\theta JA}$  is measured with the device mounted on  $1\text{in}^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.



P-Channel Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -24V, V_{GS} = 0V$			-1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1		-2.5	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS} = -10V, I_D = -6.5A$			28	m $\Omega$
		$V_{GS} = -4.5V, I_D = -5.5A$			44	m $\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = -10V, I_D = -6.5A$		24		S
<b>Drain-Source Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0V, I_S = -1.0A$			-1.2	V
$I_S$	Maximum Body-Diode Continuous Current				-2.5	A
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -15V, V_{GS} = 0V$ $f = 1.0MHz$		1490		pF
$C_{oss}$	Output Capacitance			301		pF
$C_{rss}$	Reverse Transfer Capacitance			190		pF
<b>Switching Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{DS} = -15V, I_D = -6.5A$ $V_{GS} = -10V$		26		nC
$Q_{gs}$	Gate-Source Charge			4		nC
$Q_{gd}$	Gate-Drain Charge			5		nC
$t_{D(ON)}$	Turn-On Delay Time	$V_{DD} = -15V, I_D = -1A$ $V_{GS} = -10V$ $R_{GEN} = 6\text{ ohm}$		10		ns
$t_r$	Turn-On Rise Time			5.5		ns
$t_{D(OFF)}$	Turn-Off Delay Time			26		ns
$t_f$	Turn-Off Fall Time			9		ns

- Repetitive rating, Pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ\text{C}$
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using  $\leq 10s$  junction-to-ambient thermal resistance.
- The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.